

### AMENDMENT TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application. Claim 1 IS the independent claim in the case.

#### LISTING OF CLAIMS:

1. (Previously Presented) A method of creating a stack of integrated circuits selectively connected to provide increased memory density in an application, the method comprising the steps of:

providing a carrier frame configured to have a plurality of members emergent into a window within the carrier frame;

applying a first portion of a solder-containing compound to the first side of the plurality of members;

after applying said first portion of solder-containing compound, placing a first packaged integrated circuit in contact with the plurality of members;

processing the first integrated circuit and the carrier frame with a heat source to create a first set of solder connections between the plurality of members and the first packaged integrated circuit;

after said processing step, applying a second portion of a solder-containing compound to the second side of the plurality of members of the carrier frame;

after applying the second portion of solder-containing compound, placing a second packaged integrated circuit in contact with the plurality of members; and

processing the second integrated circuit and the carrier frame with a heat source to create a second set of solder connections between the plurality of members and the second integrated circuit.

2. (Previously Presented) The method of claim 1 in which the carrier frame is provided from a carrier bed having a plurality of carrier frames.

3. (Previously Presented). The method of claim 1 in which the carrier frame and the first and second integrated circuits are further processed by separation of the plurality of members from the carrier frame.

4. (Cancelled).

5. (Cancelled).

6. (Cancelled)